Preferred Device

Power MOSFET 12 Amps, 100 Volts

P-Channel TO-220

This Power MOSFET is designed for medium voltage, high speed power switching applications such as switching regulators, converters, solenoid and relay drivers.

Features

- Silicon Gate for Fast Switching Speeds Switching Times Specified at 100°C
- Designer's Data I_{DSS}, V_{DS(on)}, V_{GS(th)} and SOA Specified at Elevated Temperature
- Rugged SOA is Power Dissipation Limited
- Source-to-Drain Diode Characterized for Use With Inductive Loads
- Pb-Free Package is Available*

MAXIMUM RATINGS (T_C = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Drain-Source Voltage	V _{DSS}	100	Vdc
Drain–Gate Voltage ($R_{GS} = 1.0 \text{ M}\Omega$)	V_{DGR}	100	Vdc
Gate–Source Voltage – Continuous – Non–repetitive $(t_p \le 50 \mu s)$	V _{GS} V _{GSM}	±20 ±40	Vdc Vpk
Drain Current – Continuous – Pulsed	I _D I _{DM}	12 28	Adc
Total Power Dissipation Derate above 25°C	P _D	75 0.6	W/°C
Operating and Storage Temperature Range	T _J , T _{stg}	-65 to 150	°C
Thermal Resistance – Junction–to–Case – Junction–to–Ambient	R _θ JC R _θ JA	1.67 62.5	°C/W
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds	T _L	260	°C

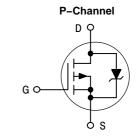
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



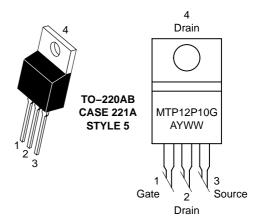
ON Semiconductor®

http://onsemi.com

12 AMPERES, 100 VOLTS $R_{DS(on)} = 300 \text{ m}\Omega$



MARKING DIAGRAM AND PIN ASSIGNMENT



ORDERING INFORMATION

Device	Package	Shipping
MTP12P10	TO-220AB	50 Units/Rail
MTP12P10G	TO-220AB (Pb-Free)	50 Units/Rail

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

Preferred devices are recommended choices for future use and best overall value.

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Characteristic		Symbol	Min	Max	Unit
OFF CHARACTERISTICS					1
Drain–Source Breakdown Voltage (V _{GS} = 0, I _D = 0.25 mA)			100	-	Vdc
Zero Gate Voltage Drain Current $(V_{DS} = Rated V_{DSS}, V_{GS} = 0)$ $(V_{DS} = Rated V_{DSS}, V_{GS} = 0, T_{J} = 125^{\circ}C)$		V _{(BR)DSS}	- -	10 100	μAdc
Gate-Body Leakage Current, Forwa	rd (V _{GSF} = 20 Vdc, V _{DS} = 0)	I _{GSSF}	-	100	nAdc
Gate-Body Leakage Current, Revers	se (V _{GSR} = 20 Vdc, V _{DS} = 0)	I _{GSSR}	_	100	nAdc
ON CHARACTERISTICS (Note 1)		l	I I		ı
Gate Threshold Voltage ($V_{DS} = V_{GS}$, $I_{D} = 1.0$ mA) $T_{J} = 100^{\circ}\text{C}$		V _{GS(th)}	2.0 1.5	4.5 4.0	Vdc
Static Drain-Source On-Resistance	(V _{GS} = 10 Vdc, I _D = 6.0 Adc)	R _{DS(on)}	_	0.3	Ω
Drain–Source On–Voltage ($V_{GS} = 10 \text{ V}$) ($I_D = 12 \text{ Adc}$) ($I_D = 6.0 \text{ Adc}$, $T_J = 100^{\circ}\text{C}$)		V _{DS(on)}	- -	4.2 3.8	Vdc
Forward Transconductance (V _{DS} = 1	5 V, I _D = 6.0 A)	9FS	2.0	_	mhos
DYNAMIC CHARACTERISTICS					•
Input Capacitance		C _{iss}	_	920	pF
Output Capacitance	$(V_{DS} = 25 \text{ V}, V_{GS} = 0, f = 1.0 \text{ MHz})$ See Figure 10	C _{oss}	-	575	
Reverse Transfer Capacitance	333 1 1 3 1 3	C _{rss}	_	200	
SWITCHING CHARACTERISTICS (Note 1) (T _J = 100°C)				
Turn-On Delay Time		t _{d(on)}	_	50	ns
Rise Time	$(V_{DD} = 25 \text{ V}, I_D = 0.5 \text{ Rated } I_D, R_G = 50 \Omega)$	t _r	-	150	- -
Turn-Off Delay Time	See Figures 12 and 13	t _{d(off)}	_	150	
Fall Time		t _f	_	150	
Total Gate Charge		Qg	33 (Typ)	50	nC
Gate-Source Charge	$(V_{DS} = 0.8 \text{ Rated } V_{DSS}, I_D = \text{Rated } I_D, V_{GS} = 10 \text{ V})$ See Figure 11	Q _{gs}	16 (Typ)	_	
Gate-Drain Charge	Goo riguio ri	Q _{gd}	17 (Typ)	-	
SOURCE-DRAIN DIODE CHARAC	FERISTICS (Note 1)	!	-!-		·
Forward On-Voltage		V_{SD}	4.0 (Typ)	5.5	Vdc
Forward Turn-On Time	$(I_S = Rated I_D, V_{GS} = 0)$	t _{on}	Limited by stray inductar		ıctance
Reverse Recovery Time	(ig = ivated ib, vgg = 0)	t _{rr}	300 (Typ)	-	ns
INTERNAL PACKAGE INDUCTANO	E (TO-204)		<u> </u>		
Internal Drain Inductance, (Measured from the contact screw on the header closer to the source pin and the center of the die)		L _d	5.0 (Typ)	-	nH
Internal Source Inductance (Measured from the source pin, 0.25" from the package to the source bond pad)			12.5 (Typ)	-	
INTERNAL PACKAGE INDUCTANO	E (TO-220)				
Internal Drain Inductance (Measured from the contact screw on tab to center of die) (Measured from the drain lead 0.25" from package to center of die)		L _d	3.5 (Typ) 4.5 (Typ)	-	nH
Internal Source Inductance (Measured from the source lead 0.25" from package to source bond pad)		L _s	7.5 (Typ)	-	1

^{1.} Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.

TYPICAL ELECTRICAL CHARACTERISTICS

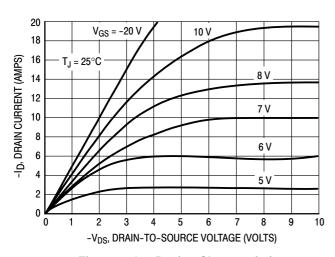


Figure 1. On-Region Characteristics

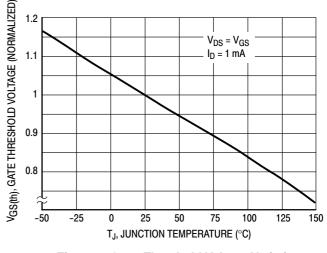


Figure 2. Gate-Threshold Voltage Variation With Temperature

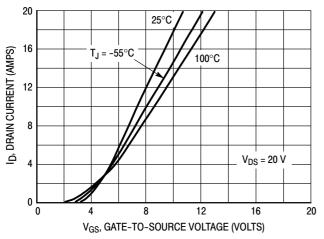


Figure 3. Transfer Characteristics

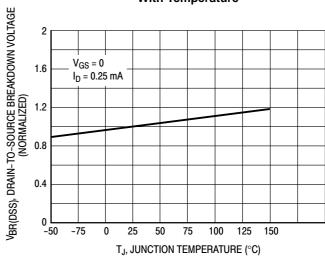


Figure 4. Normalized Breakdown Voltage versus Temperature

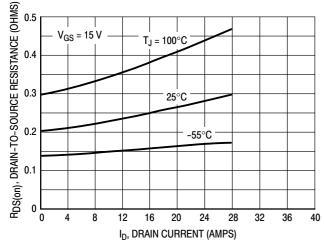


Figure 5. On-Resistance versus Drain Current

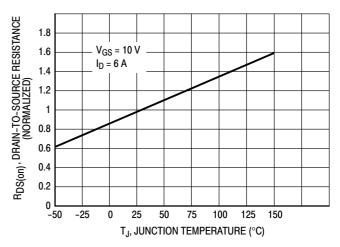


Figure 6. On–Resistance Variation
With Temperature

SAFE OPERATING AREA INFORMATION

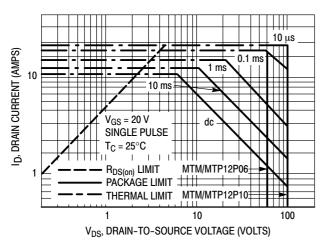


Figure 7. Maximum Rated Forward Biased Safe Operating Area

FORWARD BIASED SAFE OPERATING AREA

The FBSOA curves define the maximum drain—to—source voltage and drain current that a device can safely handle when it is forward biased, or when it is on, or being turned on. Because these curves include the limitations of simultaneous high voltage and high current, up to the rating of the device, they are especially useful to designers of linear systems. The curves are based on a case temperature of 25°C and a maximum junction temperature of 150°C. Limitations for repetitive pulses at various case temperatures can be determined by using the thermal response curves. ON Semiconductor Application Note, AN569, "Transient Thermal Resistance—General Data and Its Use" provides detailed instructions.

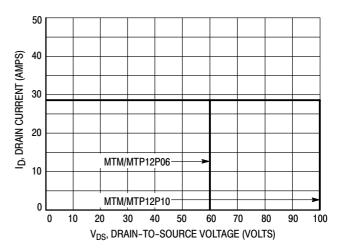


Figure 8. Maximum Rated Switching Safe Operating Area

SWITCHING SAFE OPERATING AREA

The switching safe operating area (SOA) of Figure 8 is the boundary that the load line may traverse without incurring damage to the MOSFET. The fundamental limits are the peak current, I_{DM} and the breakdown voltage, $V_{(BR)DSS}$. The switching SOA shown in Figure 8 is applicable for both turn—on and turn—off of the devices for switching times less than one microsecond.

The power averaged over a complete switching cycle must be less than:

$$\frac{T_{J(max)} - T_C}{R_{\theta JC}}$$

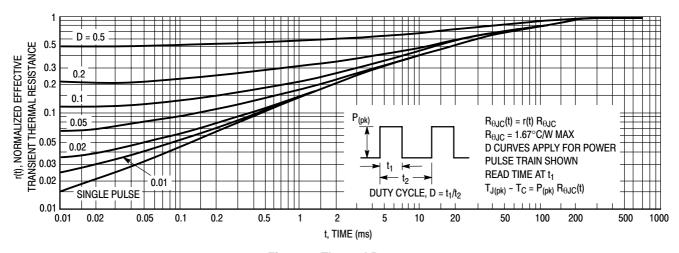
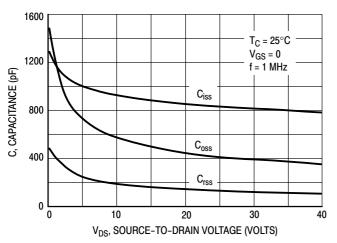


Figure 9. Thermal Response



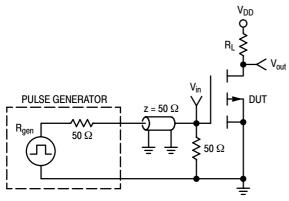
VGS, GATE SOURCE VOLTAGE (VOLTS) -2 $I_D = 12 A$ -4 -6 -8 -10 $V_{DS} = 30 \text{ V}$ -12 50 V 80 V -16 10 0 5 20 25 30 35 40 45 50 Q_q, TOTAL GATE CHARGE (nC)

 $T_J=25^{\circ}C$

Figure 10. Capacitance Variation

Figure 11. Gate Charge versus Gate-To-Source Voltage

RESISTIVE SWITCHING





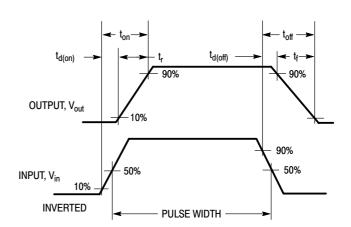
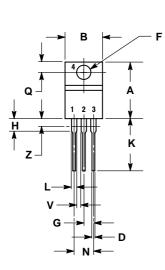
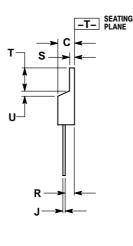


Figure 13. Switching Waveforms

PACKAGE DIMENSIONS

TO-220 CASE 221A-09 **ISSUE AB**





NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.570	0.620	14.48	15.75
В	0.380	0.405	9.66	10.28
С	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.42	2.66
Н	0.110	0.155	2.80	3.93
J	0.018	0.025	0.46	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.020	0.055	0.508	1.39
Т	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
٧	0.045		1.15	
Z		0.080		2.04

STYLE 5:

GATE PIN 1.

DRAIN 2.

3. SOURCE DRAIN

ON Semiconductor and un are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice on semiconductor and are registered readerlands of semiconductor Components industries, Ltc (SCILLC). Solitude services the inject to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

Japan Customer Focus Center Phone: 81-3-5773-3850

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

ON Semiconductor: MTP12P10 MTP12P10G